

ABSTRACT

Provided are a maleimide resin composition containing (A) one or more selected from the group consisting of a maleimide compound having two or more N-substituted maleimide groups and a derivative thereof; (B) a modified conjugated diene polymer, and (C) a thermoplastic elastomer other than the above component (B), wherein the component (B) is one resulting from modification of (b1) a conjugated diene polymer having a vinyl group in the side chain with (b2) a maleimide compound having two or more N-substituted maleimide groups; and a prepreg, a resin film, a laminated board, a printed wiring board and a semiconductor package, each using the maleimide resin composition.